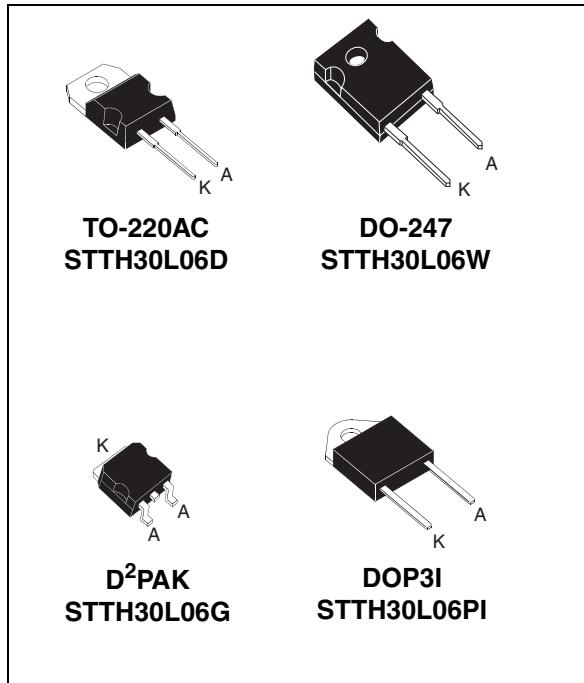


Turbo 2 ultrafast high voltage rectifier

Main product characteristics

I _{F(AV)}	30 A
V _{RRM}	600 V
T _j	175°C
V _F (typ)	1.0 V
t _{rr} (max)	65 ns



Features and benefits

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching & conduction losses
- Package insulation voltage
DOP3I: 2500 V_{RMS}

Description

The STTH30L06, which is using ST Turbo 2 600V technology, is specially suited for use in switching power supplies, and industrial applications, as rectification and discontinuous mode PFC boost diode.

Order codes

Part Number	Marking
STTH30L06D	STTH30L06D
STTH30L06G	STTH30L06G
STTH30L06G-TR	STTH30L06G
STTH30L06W	STTH30L06W
STTH30L06PI	STTH30L06PI

1 Characteristics

Table 1. Absolute ratings (limiting values)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			600	V
$I_{F(RMS)}$	RMS forward voltage			50	A
$I_{F(AV)}$	Average forward current	TO-220AC / TO-247 / D ² PAK	$T_c = 125^\circ C \delta = 0.5$	30	A
		DOP3I	$T_c = 95^\circ C \delta = 0.5$		
I_{FSM}	Surge non repetitive forward current		$t_p = 10 \text{ ms sinusoidal}$	160	A
T_{stg}	Storage temperature range			-65 to + 175	°C
T_j	Maximum operating junction temperature			175	°C

Table 2. Thermal resistance

Symbol	Parameter		Value (max).	Unit
$R_{th(j-c)}$	Junction to case	TO-220AC / TO-247 / D ² PAK		1.1
		DOP3I		1.7

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
I_R ⁽¹⁾	Reverse leakage current	$T_j = 25^\circ C$	$V_R = V_{RRM}$			25	μA
		$T_j = 150^\circ C$			80	800	
V_F ⁽²⁾	Forward voltage drop	$T_j = 25^\circ C$	$I_F = 30 A$			1.55	V
		$T_j = 150^\circ C$			1.0	1.25	

1. Pulse test: $t_p = 5 \text{ ms}, \delta < 2\%$ 2. Pulse test: $t_p = 380 \mu\text{s}, \delta < 2\%$ To evaluate the conduction losses use the following equation: $P = 0.95 \times I_{F(AV)} + 0.010 I_{F(RMS)}^2$ **Table 4. Dynamic Characteristics**

Symbol	Parameter	Test conditions			Min	Typ	Max	Unit
t_{rr}	Reverse recovery time	$T_j = 25^\circ C$	$I_F = 0.5 A$	$I_{rr} = 0.25 A$	$I_R = 1 A$		65	ns
			$I_F = 1 A$	$dI_F/dt = 50 A/\mu\text{s}$	$V_R = 30 V$	65	90	
I_{RM}	Reverse recovery current	$T_j = 125^\circ C$	$I_F = 30 A$		$V_R = 400 V$		11.5	16
$dI_F/dt = 100 A/\mu\text{s}$								A
t_{fr}	Forward recovery time	$T_j = 25^\circ C$	$I_F = 30 A$		$dI_F/dt = 100 A/\mu\text{s}$		500	ns
$V_{FR} = 1.1 \times V_{Fmax}$								
V_{FP}	Forward recovery voltage	$T_j = 25^\circ C$	$I_F = 30 A$		$dI_F/dt = 100 A/\mu\text{s}$		2.5	
$V_{FR} = 1.1 \times V_{Fmax}$								V

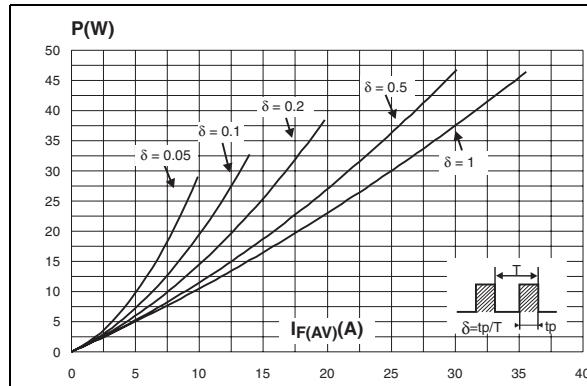
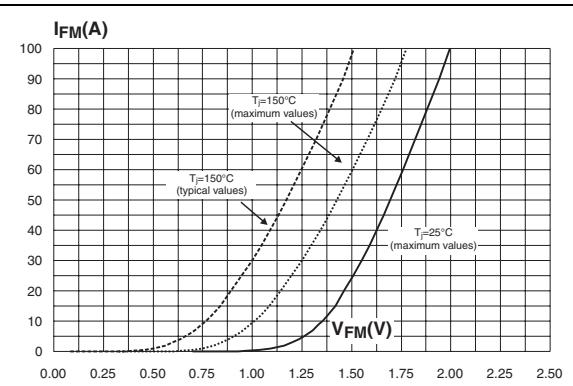
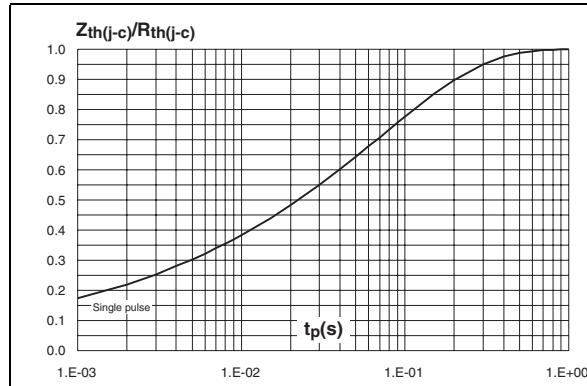
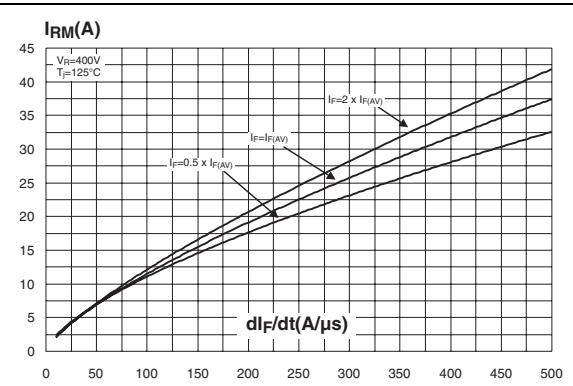
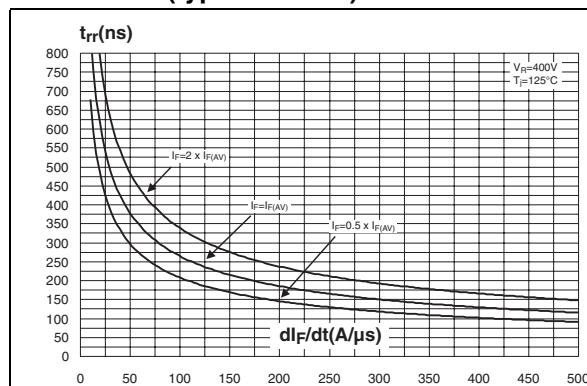
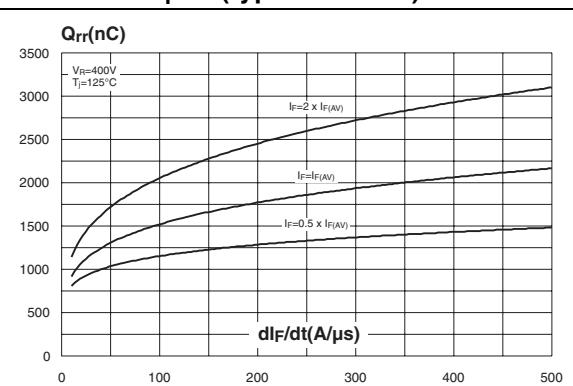
Figure 1. Conduction losses versus average forward current**Figure 2. Forward voltage drop versus forward current****Figure 3. Relative variation of thermal impedance junction to case versus pulse duration****Figure 4. Peak reverse recovery current versus dI_F/dt (typical values)****Figure 5. Reverse recovery time versus dI_F/dt (typical values)****Figure 6. Reverse recovery charges versus dI_F/dt (typical values)**

Figure 7. Reverse recovery softness factor versus dl_F/dt (typical values)

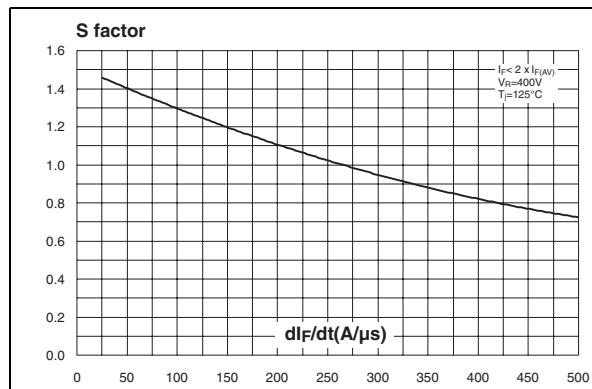


Figure 8. Relative variations of dynamic parameters versus junction temperature

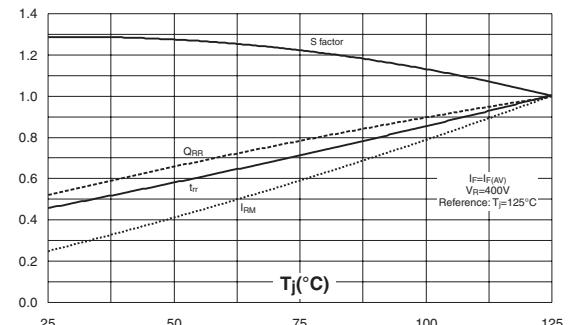


Figure 9. Transient peak forward voltage versus dl_F/dt (typical values)

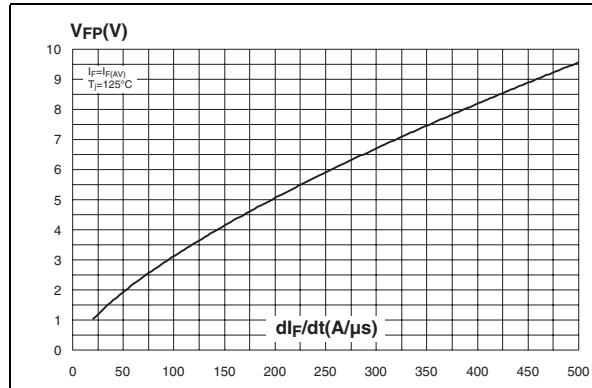


Figure 10. Forward recovery time versus dl_F/dt (typical values)

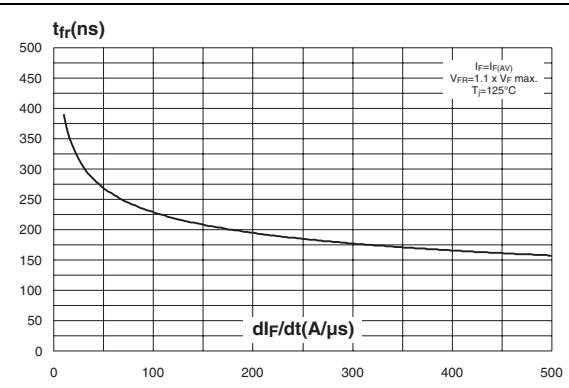


Figure 11. Junction capacitance versus reverse voltage applied (typical values)

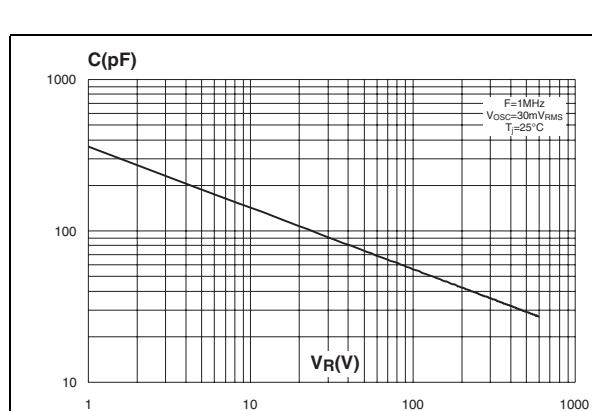
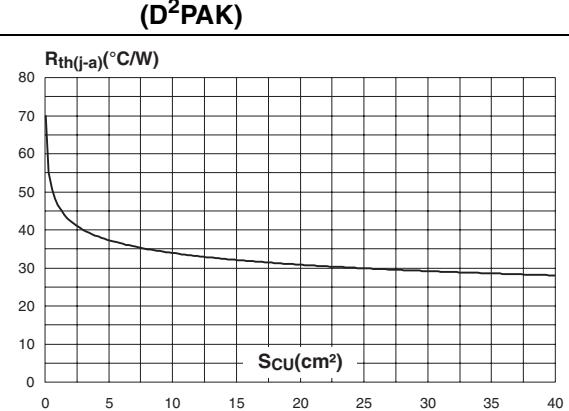


Figure 12. Thermal resistance junction to ambient versus copper surface under tab (epoxy FR4, $e_{CU}=35\mu m$) (D²PAK)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 Nm (TO-220FPAC) / 0.55 Nm (TO-220AC)
- Maximum torque value: 1.0 Nm (TO-220FPAC) / 0.70 Nm (TO-220AC)

Table 5. D²PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 13. D²PAK footprint (dimensions in mm)

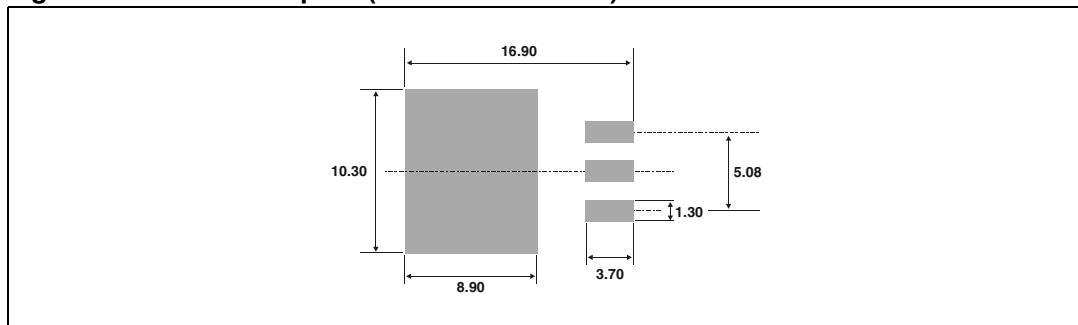
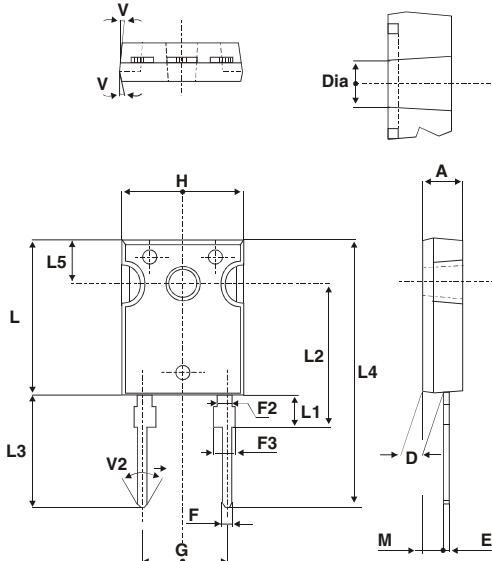


Table 6. DO247 dimensions

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00				0.078
F3	2.00		2.40	0.078		0.094
G		10.90				0.429
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50				0.728
L3	14.20		14.80	0.559		0.582
L4		34.60				1.362
L5		5.50				0.216
M	2.00		3.00	0.078		0.118
V		5°				5°
V2		60°				60°
Dia.	3.55		3.65	0.139		0.143



The technical drawing illustrates the DO247 package with two views: a top view showing lead outlines and internal features, and a side view showing the profile. Key dimensions labeled include: A (height), D (width), E (lead thickness), F (lead spacing), F2 (lead length), F3 (lead pitch), G (lead pitch), H (body height), L (body width), L1 (lead thickness), L2 (lead pitch), L3 (lead thickness), L4 (lead pitch), L5 (lead thickness), M (lead thickness), V (lead angle), V2 (lead angle), and Dia. (lead diameter). The top view also shows internal features like the body height (H), lead pitch (F2), lead thickness (F3), lead angle (V2), and lead diameter (Dia.).

Table 7. TO-220AC dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

Table 8. DOP3I dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	1.20	1.40	0.047	0.055
c	1.45	1.55	0.057	0.061
c1	0.50	0.70	0.020	0.028
D	12.15	13.10	0.474	0.516
E	15.10	15.50	0.594	0.610
E1	7.55	7.75	0.297	0.305
e	10.80	11.30	0.425	0.445
G	20.4	21.10	0.815	0.831
L	14.35	15.60	0.565	0.614
P	4.08	4.17	0.161	0.164
Q	2.70	2.90	0.106	0.114
R	4.60 typ.		0.181 typ.	
Y	15.80	16.50	0.622	0.650

3 Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STTH30L06D	STTH30L06D	TO-220AC	1.90 g	50	Tube
STTH30L06G	STTH30L06G	D ² PAK	1.48 g	50	Tube
STTH30L06G-TR	STTH30L06G	D ² PAK	1.48 g	1000	Tape & reel
STTH30L06W	STTH30L06W	DO-247	4.40 g	30	Tube
STTH30L06PI	STTH30L06PI	DOP3I	4.46 g	30	Tube

4 Revision history

Date	Revision	Changes
07-Sep-2004	1	First issue.
21-Oct-2004	2	DOP3I package added.
11-Jan-06	3	On page 2: – $I_{F(RMS)}$ corrected from 30 A to 50 A – $I_{F(AV)}$ corrected from 50 A to 30 A
10-Aug-2006	4	Reformatted to current standards. SOD-93 packaage removed.

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